

# Tracking Detectors for Belle II

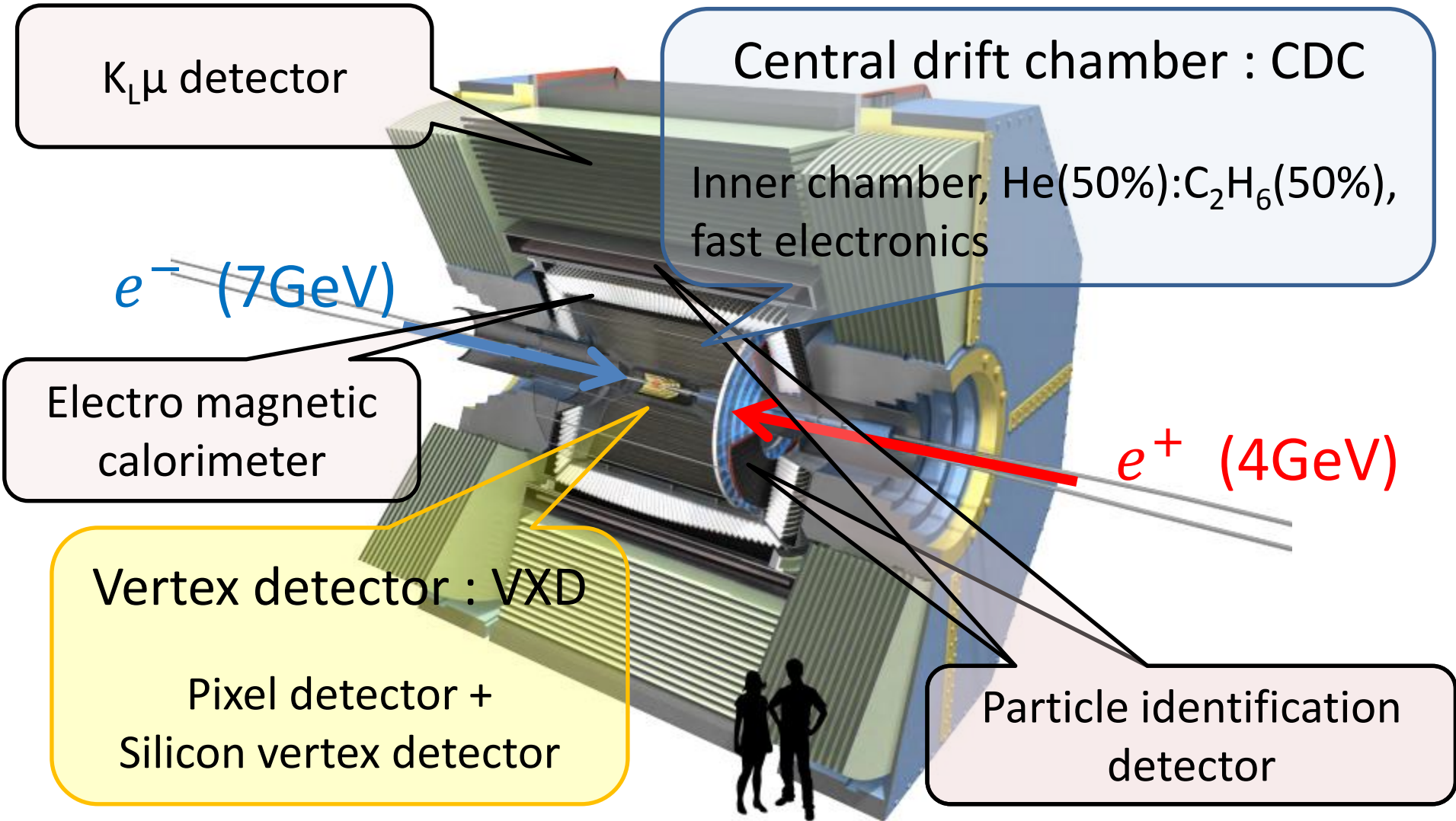
Tomoko Iwashita(Kavli IPMU (WPI))

Beauty 2014

# Introduction

- Belle II experiment is upgrade from Belle
  - Target luminosity :  $8 \times 10^{35} \text{ cm}^{-2} \text{ s}^{-1}$
  - Target physics : New physics search
- The charged particle tracking in Belle II
  - In order to achieve the high background immunity and high rate capability, the detector system Belle II must introduce the available best solutions.

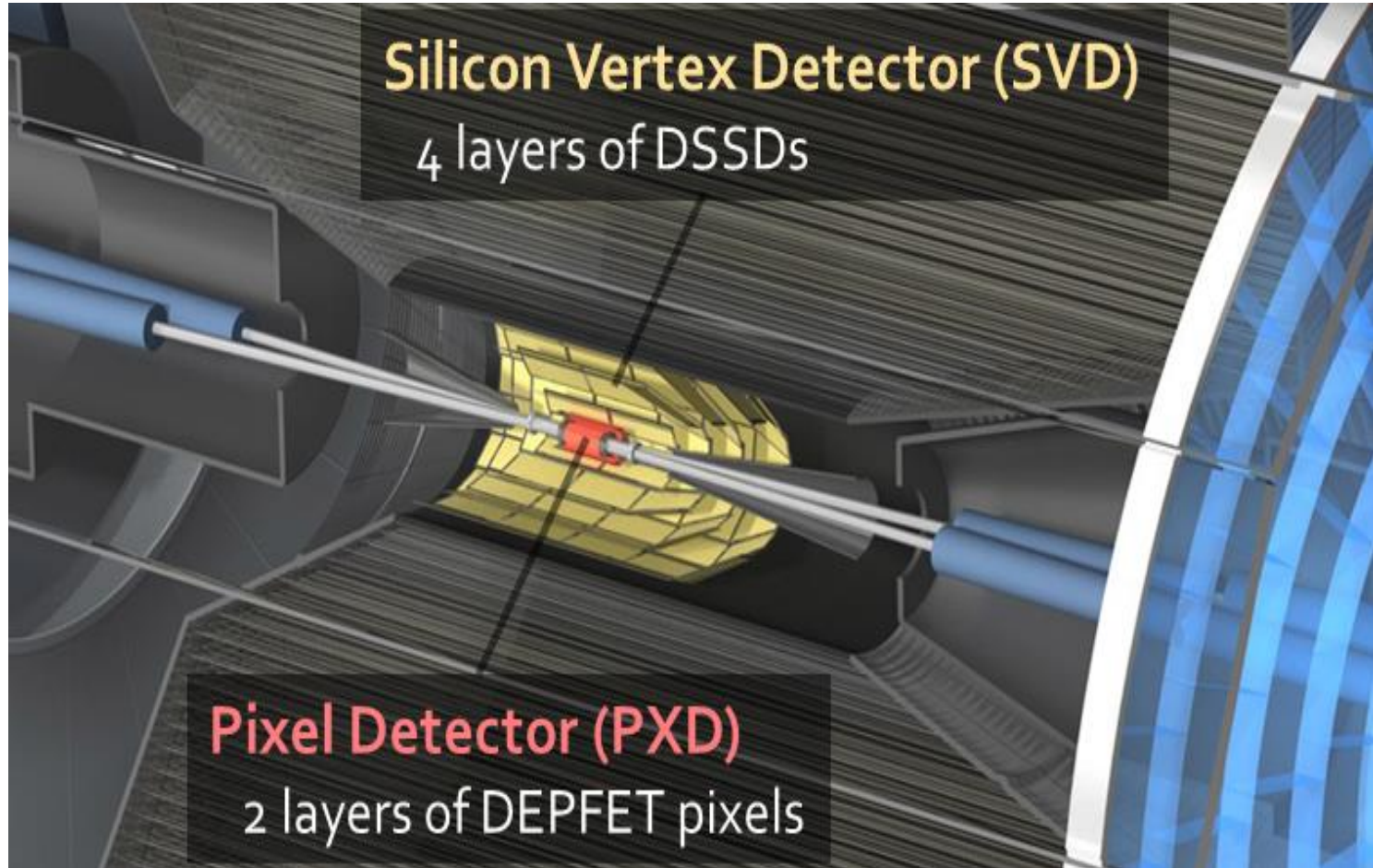
# Belle II detector



# Improvements in the vertex detector system (VXD)

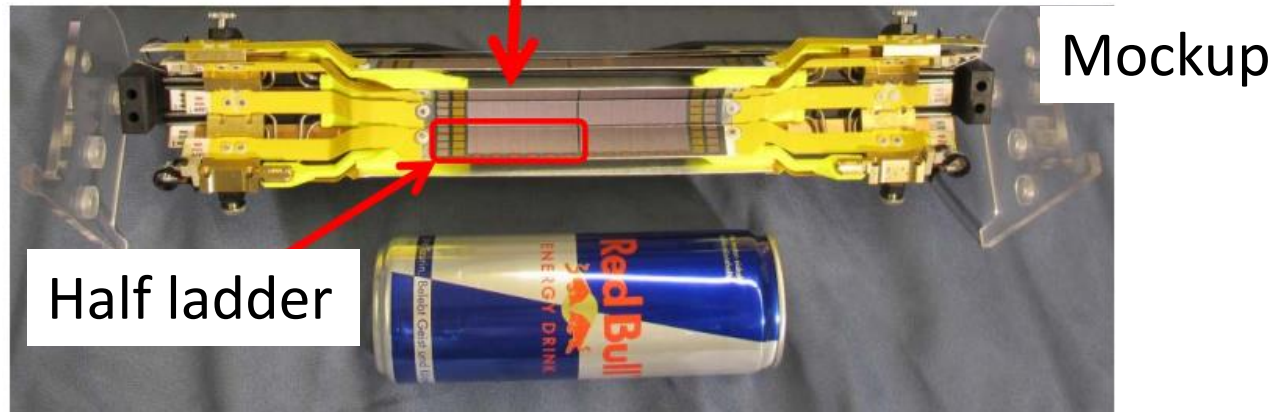
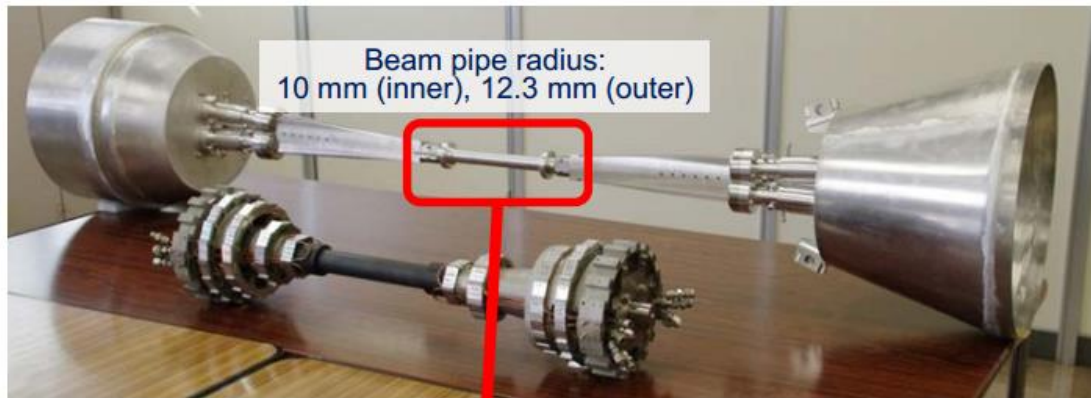
1. Introduce 2-layers DEPFET pixel sensors
  - Placed close to the IP (at  $r=14\text{mm}$  and  $22\text{mm}$ )
  - Thin sensor ( $75\mu\text{m}$  thick) to reduce multiple scattering
    - ➔ Good for time dependent CP measurement
2. Silicon strip detectors cover larger volume
  - From layer 3 ( $r=38\text{mm}$ ) up to layer 6 ( $r=135\text{mm}$ )
  - Acceptable occupancy
  - Improved reconstruction efficiency for B vertex reconstruction with
    - $K_S \rightarrow \pi^+\pi^-$
    - i.e.  $B^0 \rightarrow K_S K_S$ ,  $B^0 \rightarrow K_S K_S K_S$ ,  $B^0 \rightarrow K_S \pi^0$ , etc.

# Vertex detector



# PXD configuration

- Two layers of DEPFET pixels
- Inner radius = 1.4 cm, outer radius = 2.2 cm



# Half ladder of DEPFET PXD

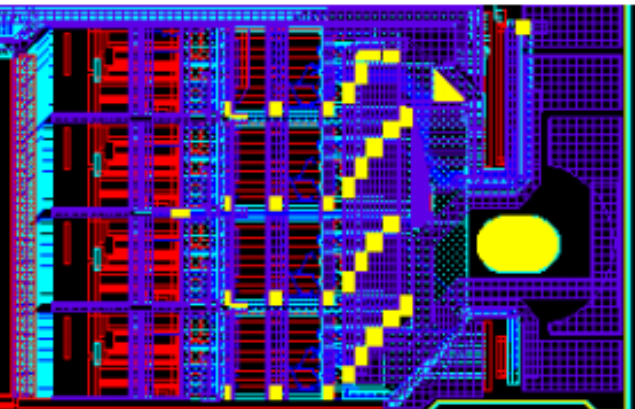
	Inner layer (L1)	Outer layer (L2)
# modules	8	12
Distance from IP (cm)	1.4	2.2
Thickness ( $\mu\text{m}$ )	75	75
Total # pixels	$3.072 \times 10^6$	$4.608 \times 10^6$
Pixel size ( $\mu\text{m}^2$ )	55, 60 x 50	70, 85 x 50
Sensitive area ( $\text{mm}^2$ )	44.8 x 12.5	61.44 x 12.5
Sensor length (mm)	90	123
Frame/Row rate	50 kHz / 10 MHz	50 kHz / 10 MHz

**256 x 250 pixels**

- $55 \times 50 \mu\text{m}^2$  (L1)
- $70 \times 50 \mu\text{m}^2$  (L2)

**512 x 250 pixels**

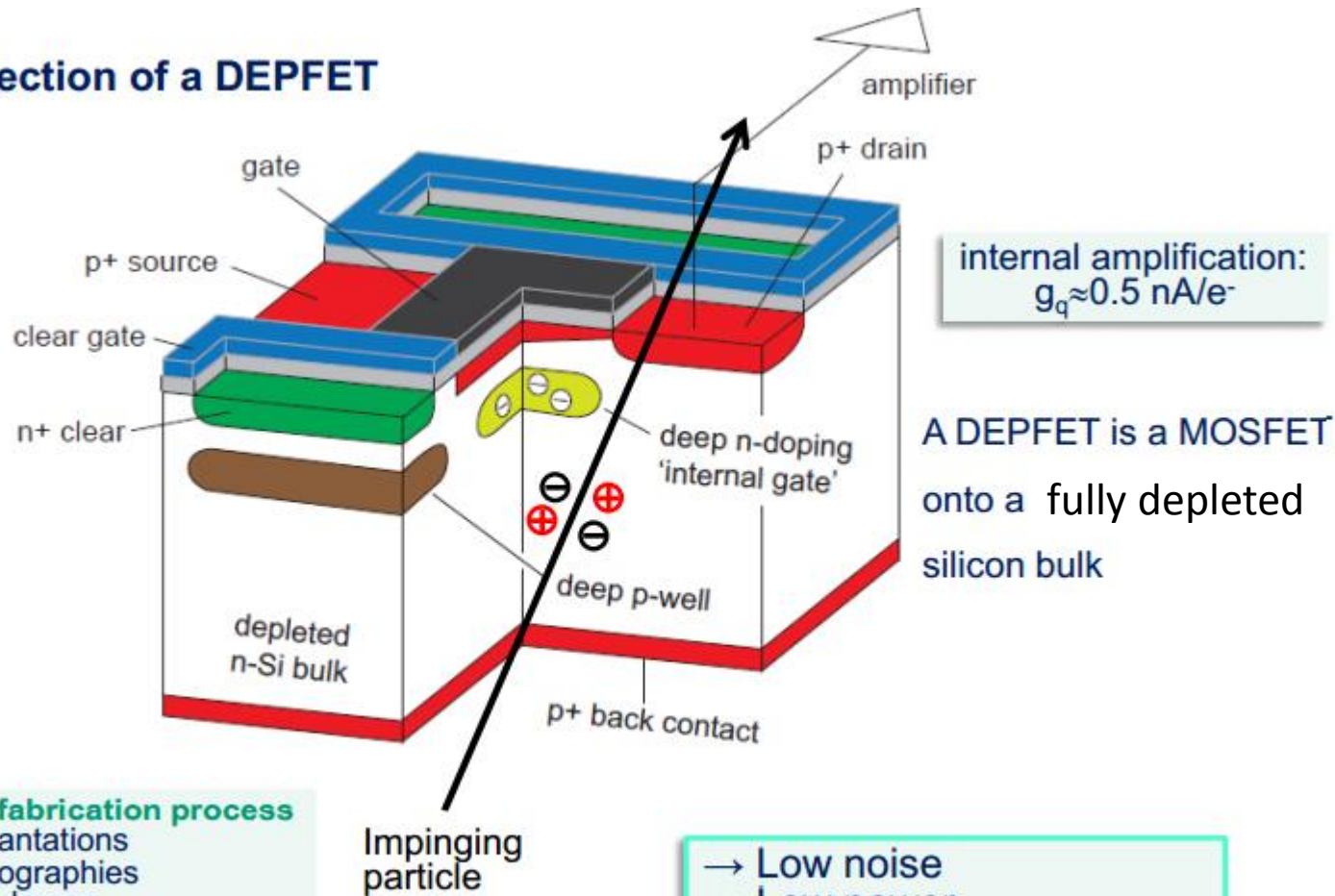
- $60 \times 50 \mu\text{m}^2$  (L1)
- $85 \times 50 \mu\text{m}^2$  (L2)



# DEPFET

(Depleted p-channel field effective transistor)

## Cross Section of a DEPFET



A DEPFET is a MOSFET onto a fully depleted silicon bulk

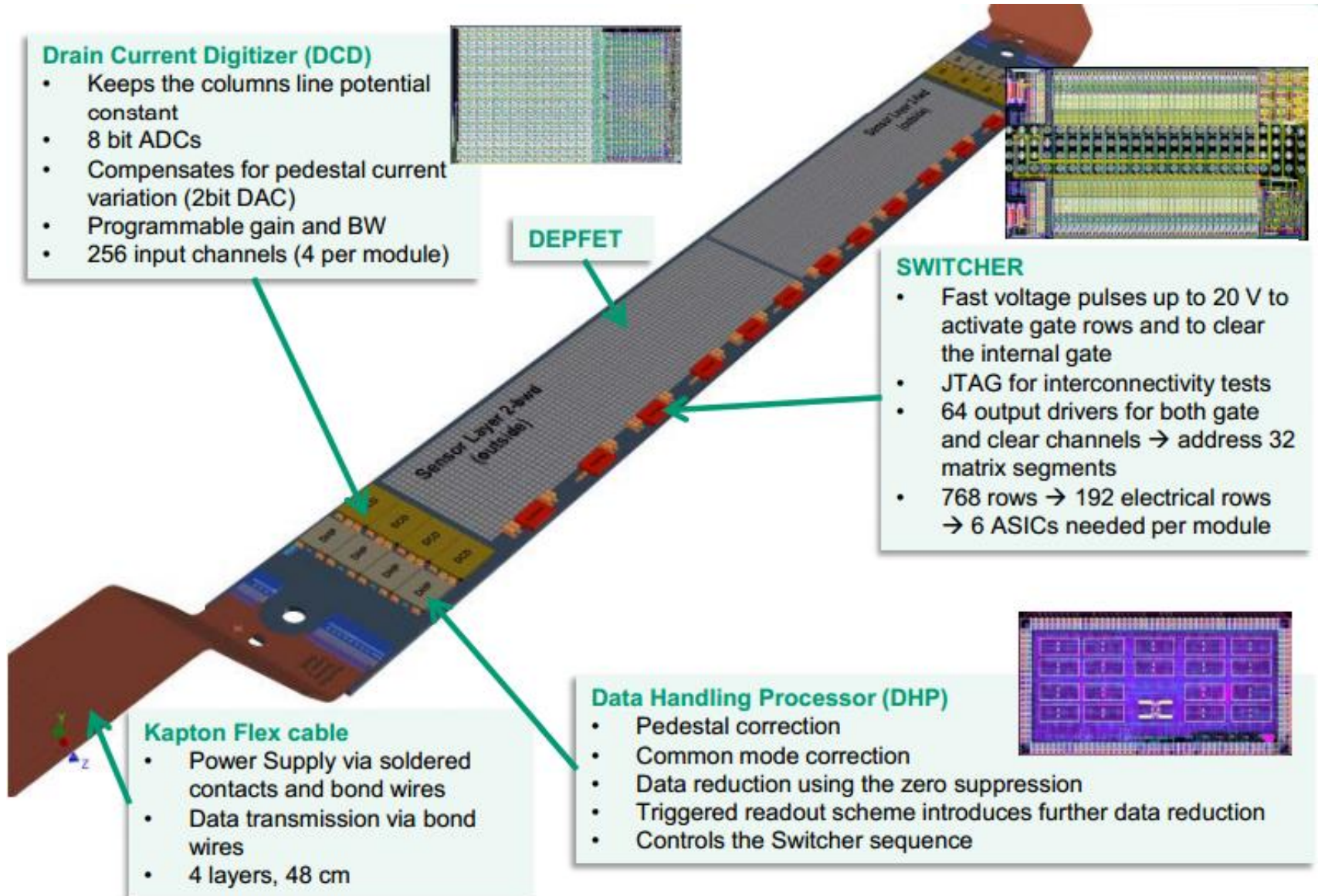
### 90 steps fabrication process

- 9 implantations
- 19 lithographies
- 2 Poly-layers
- 2 Aluminum layers
- 1 Copper layer
- Back side processing

- Low noise
- Low power
- High signal/noise-ratio
- Non-destructive readout

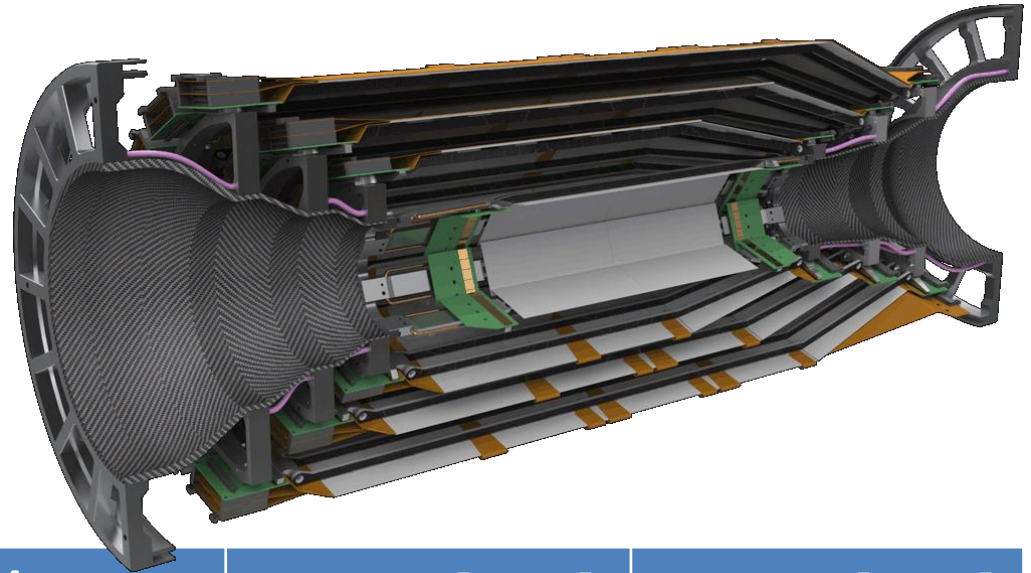


# Control and readout electronics



# SVD configuration

- 4 cylindrical layers

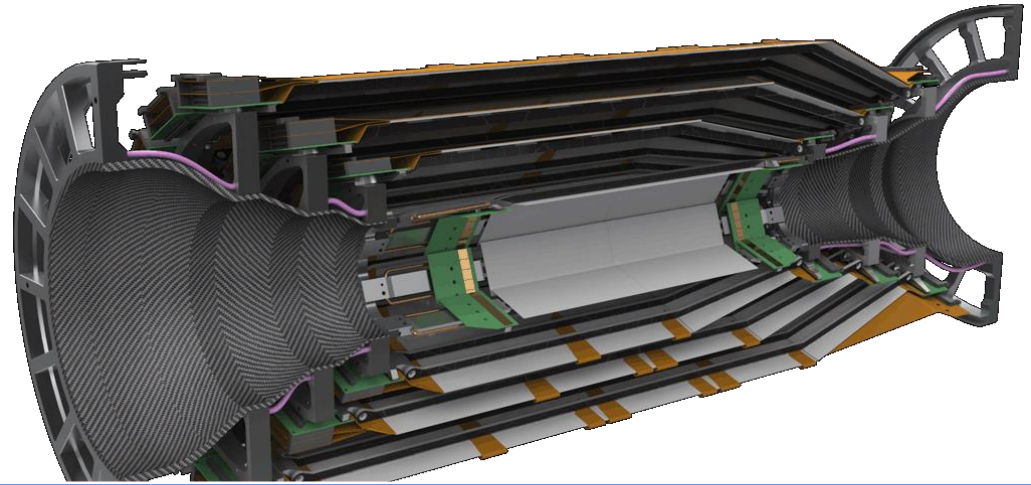


Layer	# of ladders	Sensors/ladder	Radius [mm]	Length [mm]
6	16	5	135	701
5	12	4	104	579
4	10	3	80	456
3	7	2	38	404

\*Length shows between FW and BW mount point<sup>10</sup>

# SVD configuration

- 4 cylindrical layers

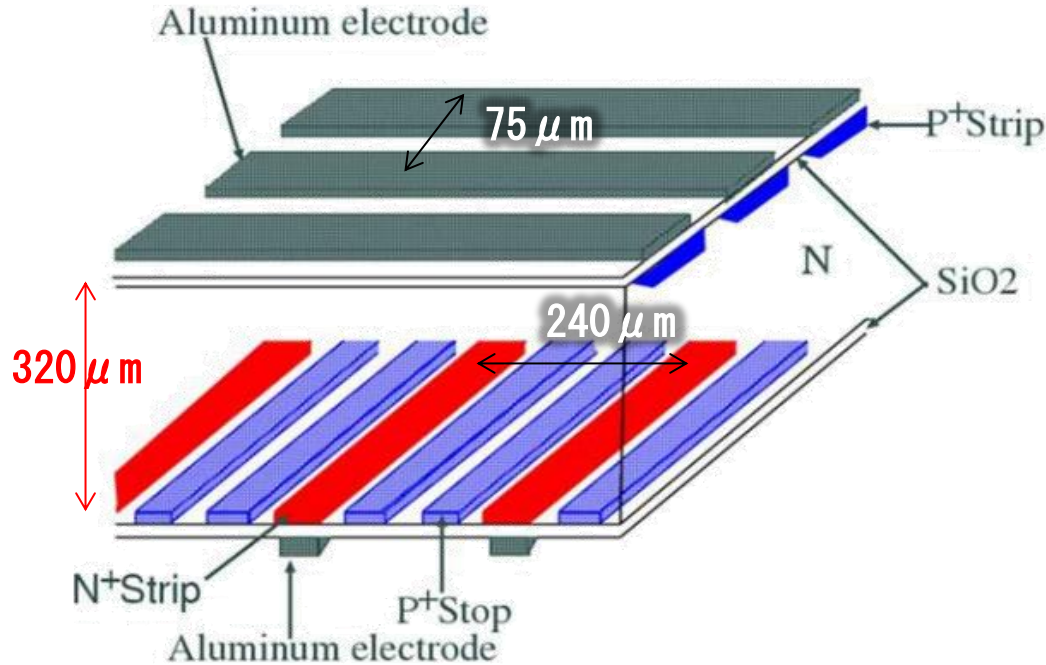


Layer	Assembly site
6	IPMU
5	HEPHY
4	TIFR at IPMU
3	Melbourne
Forward and backward module : Pisa	

lengths between ... and ... means points

# Double sided Si detector : DSSD

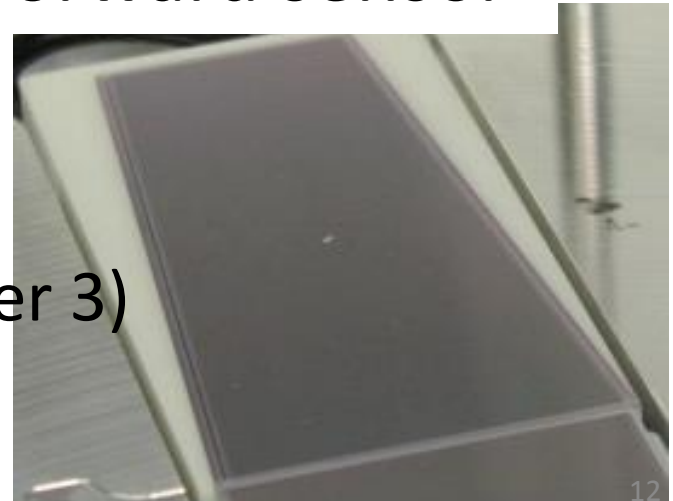
Large rectangular DSSD



Barrel sensor



Forward sensor



## Kinds of sensors

- Slim rectangular for barrel (For layer 3)
- Large rectangular for barrel
- Trapezoidal for forward

# Double sided Si detector : DSSD

Large rectangular DSSD

Barrel sensor

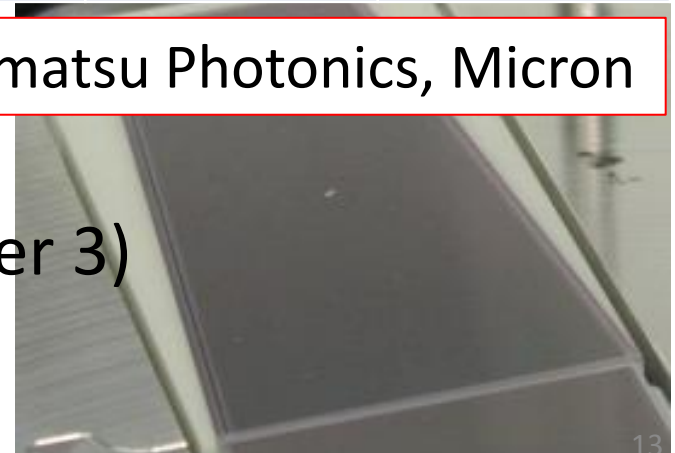
Sensor type	# of strips (P)	# of strips (N)	Pitches z [ $\mu\text{m}$ ]	Pitches $r\phi$ [ $\mu\text{m}$ ]	Thickness [ $\mu\text{m}$ ]
Slim rectangular	768	768	160	50	320
Large rectangular	768	512	240	75	320
Trapezoidal	768	512	240	50-75	300



Manufacturer: Hamamatsu Photonics, Micron

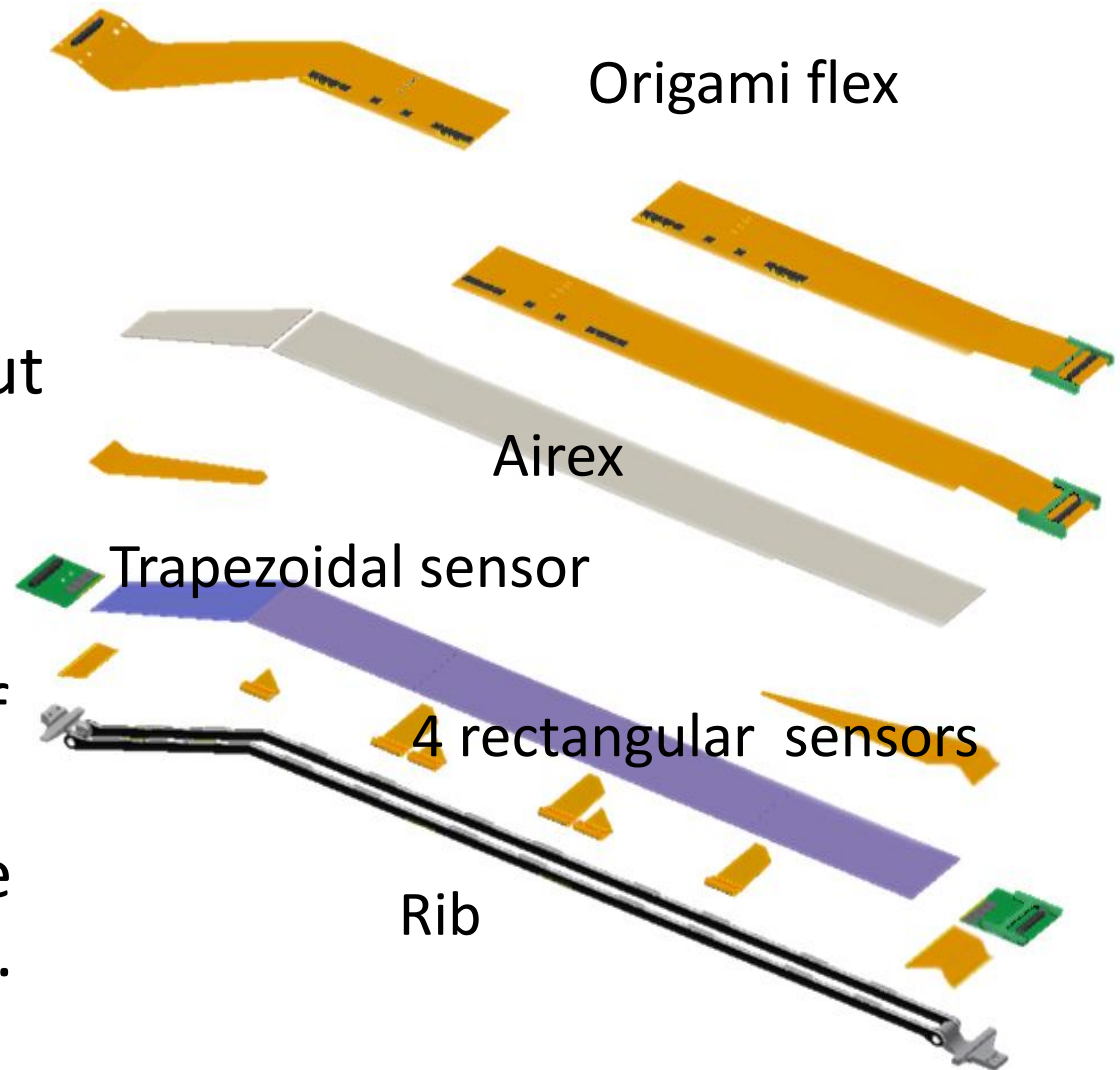
## Kinds of sensors

- Slim rectangular for barrel (For layer 3)
- Large rectangular for barrel
- Trapezoidal for forward



# Ladder structure (Layer 6)

- Precise alignment of the sensor modules
- Each DSSD is read out with individual readout hybrid
- Thanks to the slant structure, the polar angular acceptance of Belle, ranging from  $17^\circ$  to  $150^\circ$ , can be covered with 5 DSSDs.



# Ladder structure (Layer 6)

- Precise alignment of the sensor modules
- Each with its own hybrid
- Thanks to the structure angular Belle, 17° cover



Origami flex



sensors

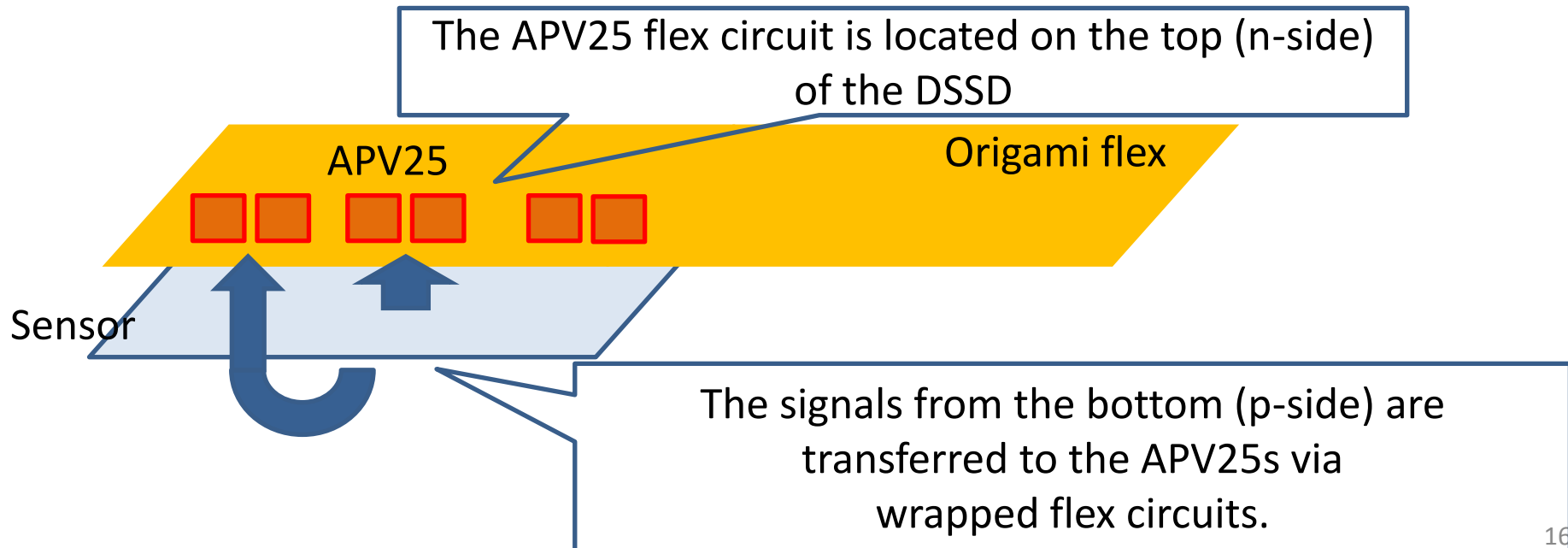
# The chip on sensor scheme

## APV25

- High radiation hardness
- Short shaping time and long pipeline
- Low noise

- APV25 is adopted for the readout

- If electrical wiring is long, capacitive noise become big
- APV25 should be located to right above on DSSD

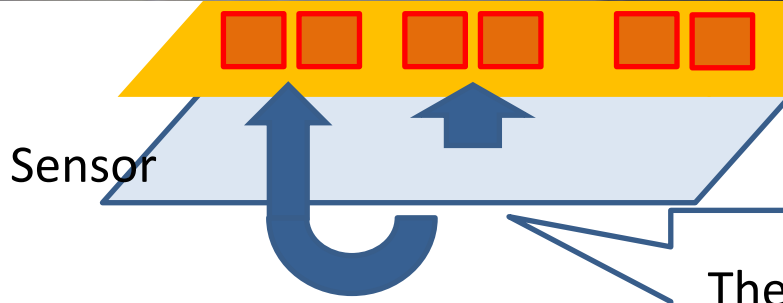
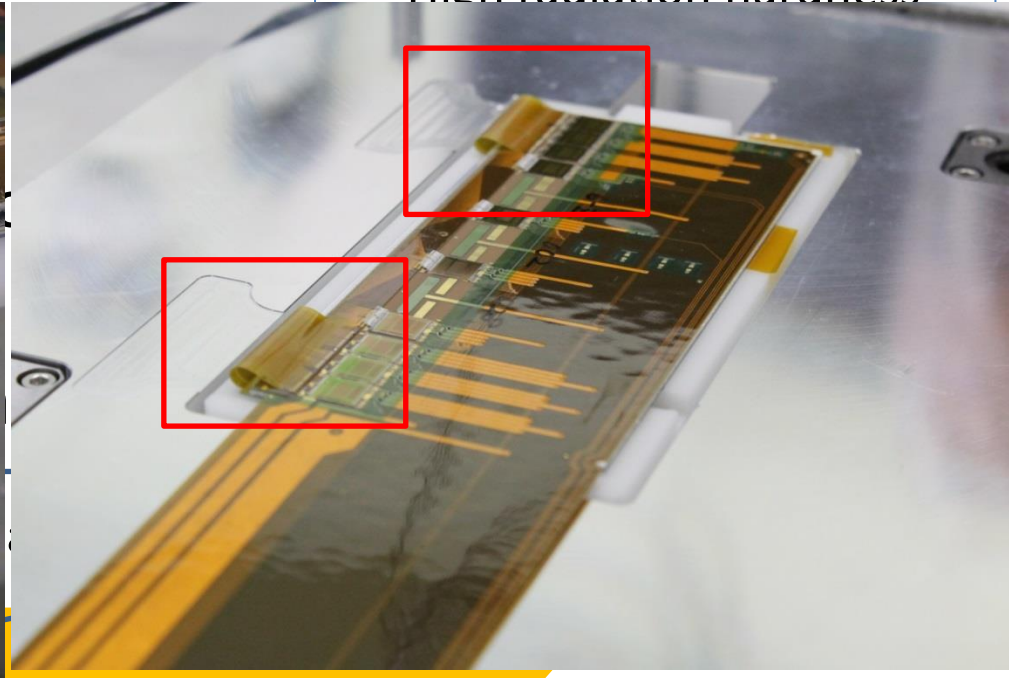
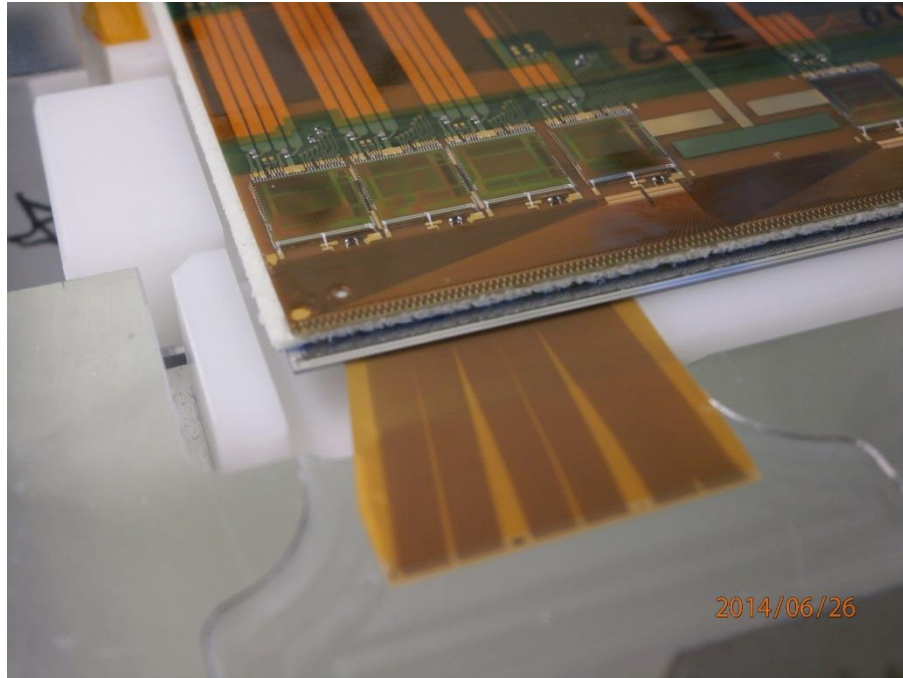




# The chip on sensor scheme

APV25

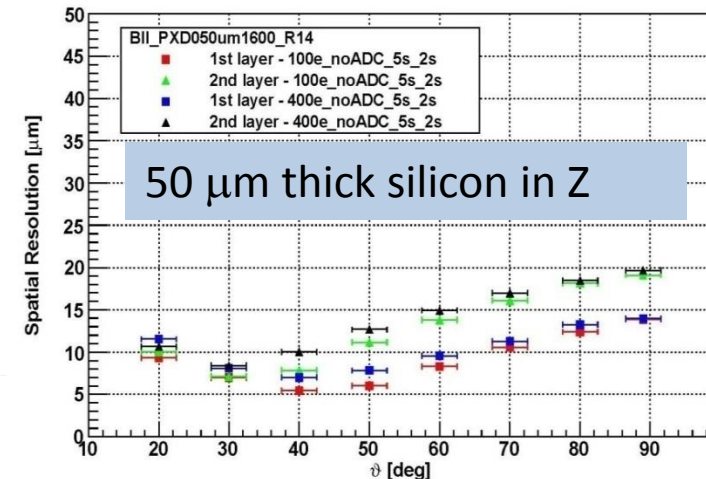
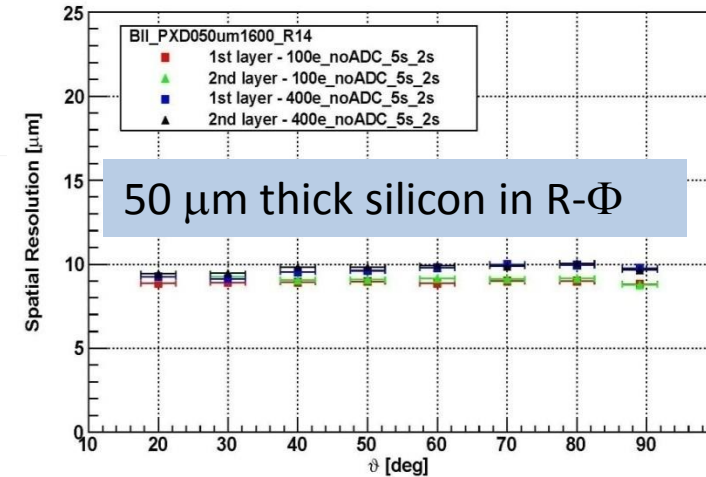
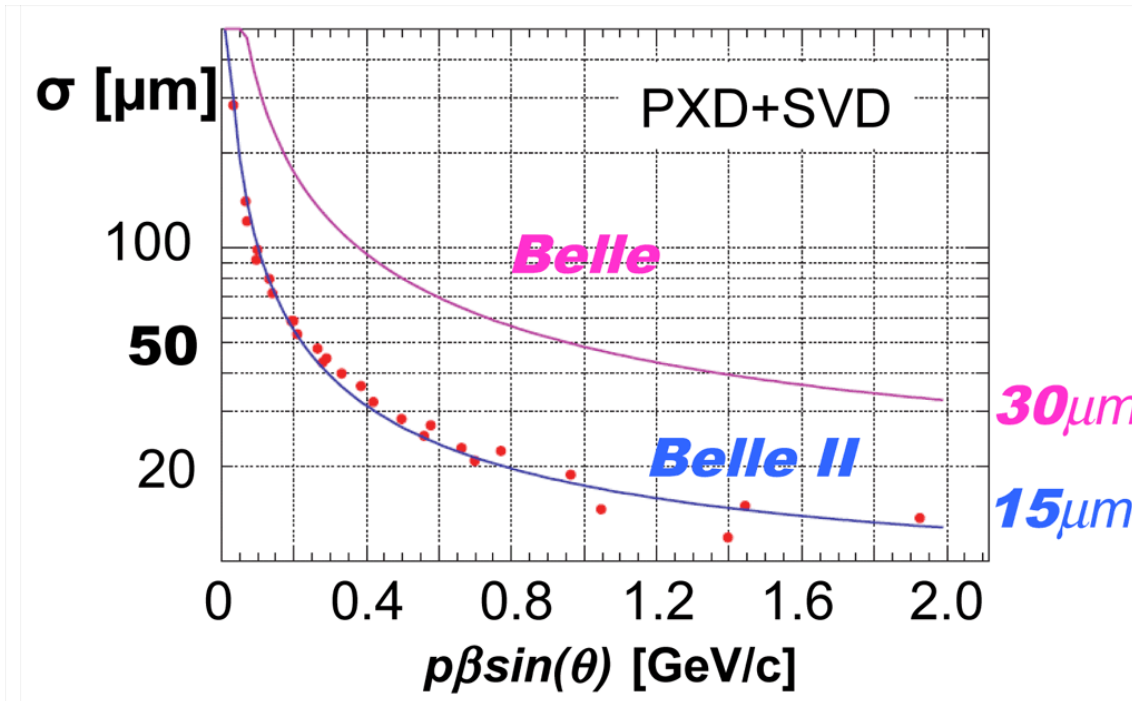
- High radiation hardness



The tail side signals of the DSSD are transmitted to the APV25s via wrapped flex circuit.

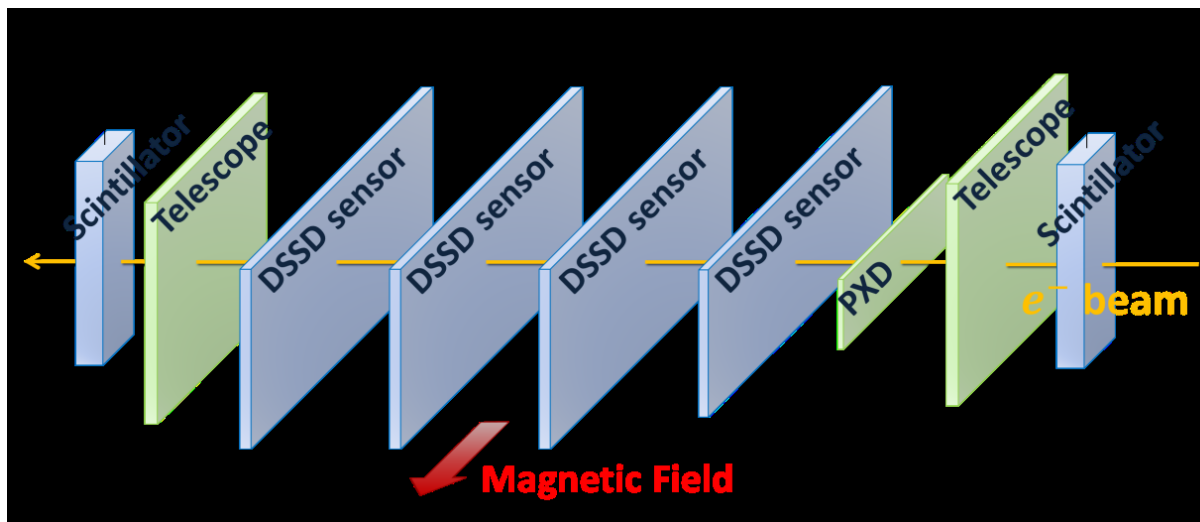
# Spatial Resolution of the Belle II detector

MC simulation for 50 and 75  $\mu\text{m}$  thick silicon: intrinsic resolution in R- $\Phi$  and Z

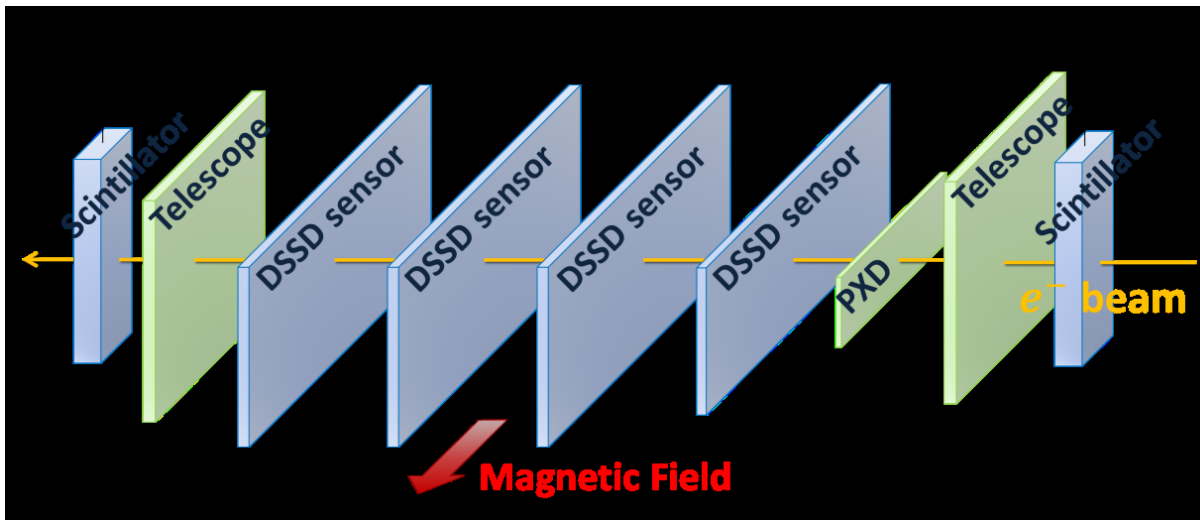
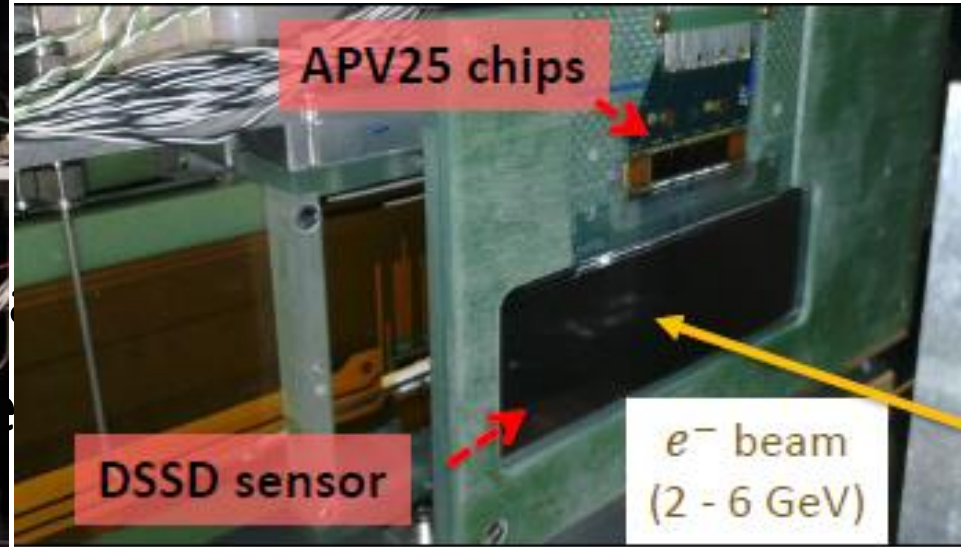
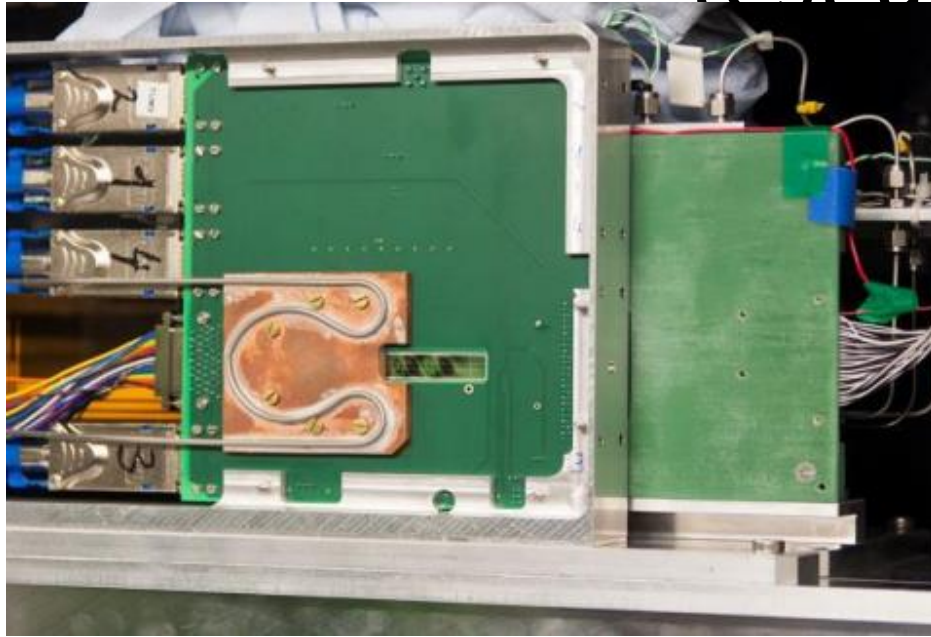


# 2014 Jan. PXD + SVD combined beam test at DESY

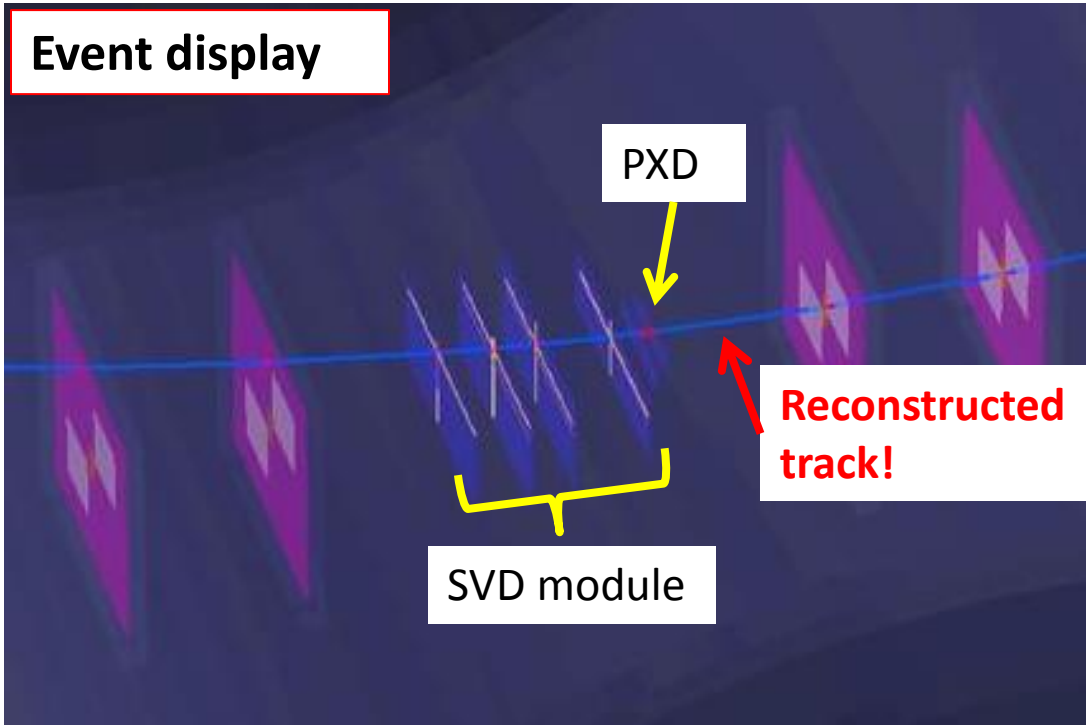
- Full Belle II readout chain of SVD + PXD
- Trigger rate:  $\sim 400$  Hz
- Confirmation of correct data processing
- Stable operation of the readout during the beam test (about 3 weeks)



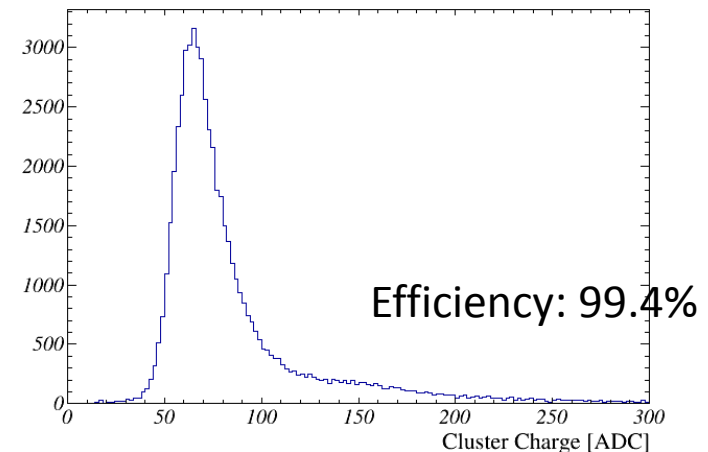
# 2014 Jan. PXD + SVD combined beam test at DESY



# Analysis result of beam test



**Cluster charge distribution of SVD**



- Belle II SVD + PXD readout system has been verified
- Stable operation of the SVD readout system during the beam test
- Confirmed the PXD readout scheme with ROI (region of interest)
- SVD+PXD alignment and track reconstruction have been performed with beam data

# Belle II central drift chamber : CDC

The Belle I experiment proved that the He:C<sub>2</sub>H<sub>6</sub>=50:50 gas and aluminum alloy field wires is an excellent solution realizing a low-material drift chamber

## 1. Set the small-cells for CDC

- Adopts the small cells in inner 8 layers.
- Reduce the occupancy by reducing the cell size.

## 2. Larger radius of CDC than Belle

- In Belle II, the volume of the PID device (TOP) is smaller than Belle's (ACC+TOF).

→ Better momentum resolution than Belle

# Belle II central drift chamber : CDC

The Belle I experiment proved that the He:C<sub>2</sub>H<sub>6</sub>=50:50 gas and aluminum alloy field wires is an excellent solution realizing a low-material drift chamber

- CDC cylinder size
  - Inner 77mm→160mm
  - Outer 880mm→1130mm
- Increase sense wires
  - 8400→14330

for CDC (Belle II CDC)

cells in inner 8 layers.

Belle CDC

efficiency by reducing the cell size.

C than Belle

radius of the PID device (TOP) is

smaller than that of Belle I (ACC+TOF).

→ Better momentum resolution than Belle

# Inner chamber

- CDC is consisted from two parts
  - Inner chamber and main chamber
- Inner chamber (small-cell chamber) is in order for high background immunity

## Small-cell chamber

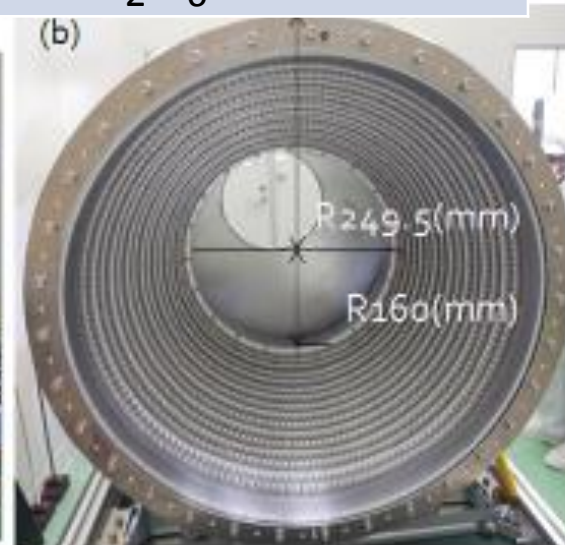
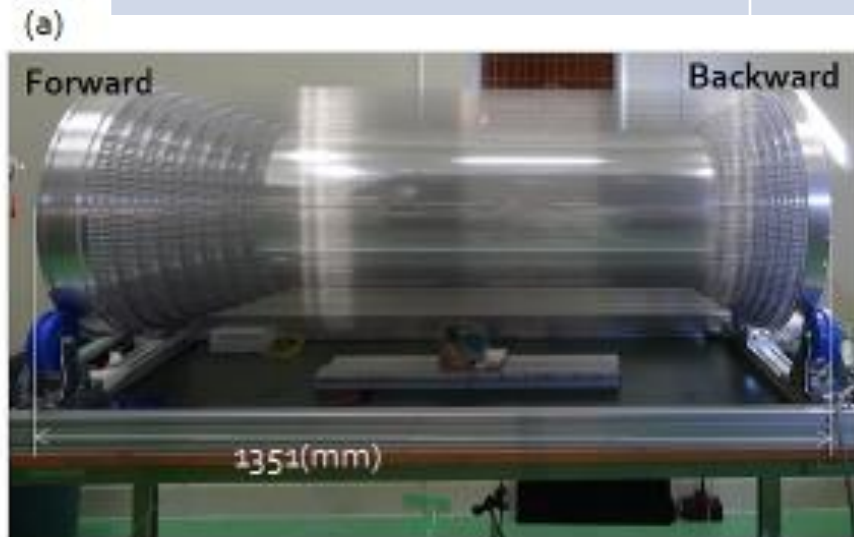




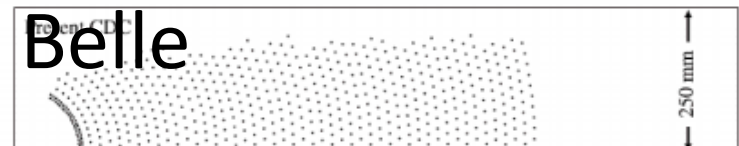
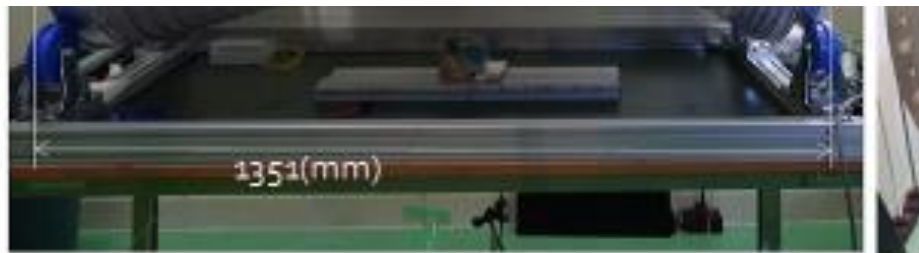
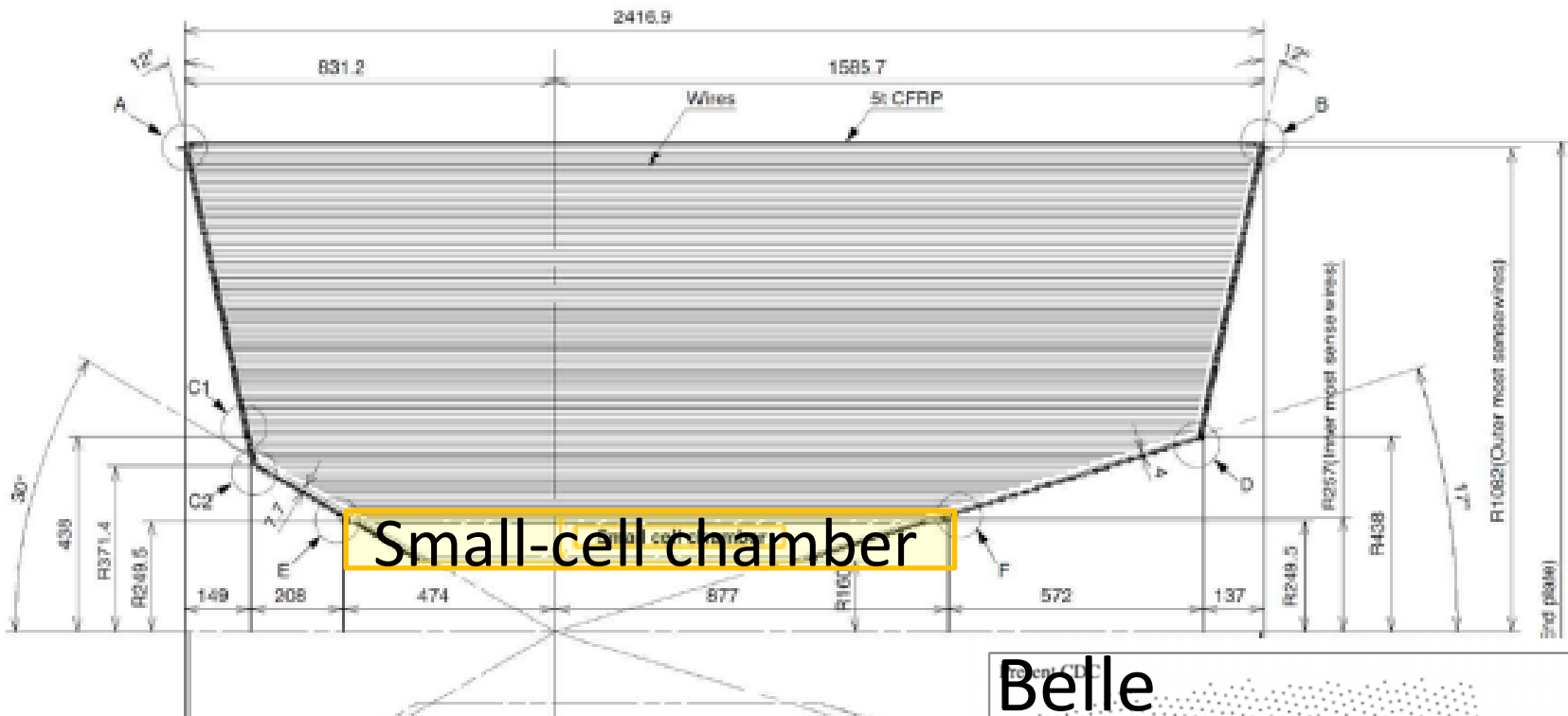
# Inner chamber

- CDC
- In
- Inne
- cou

Contents	
Inner layer radius	168 [mm]
Outer layer radius	238 [mm]
# of layers	8
# of sense wires	1280
Gas	He : C <sub>2</sub> H <sub>6</sub> = 50 : 50

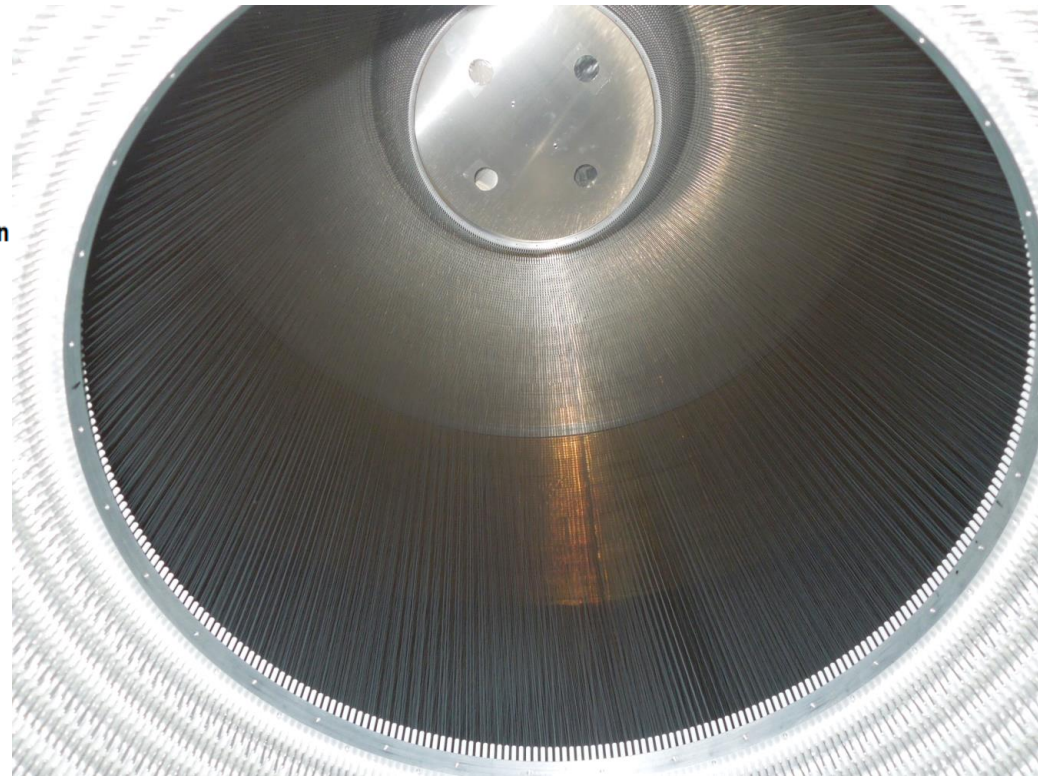
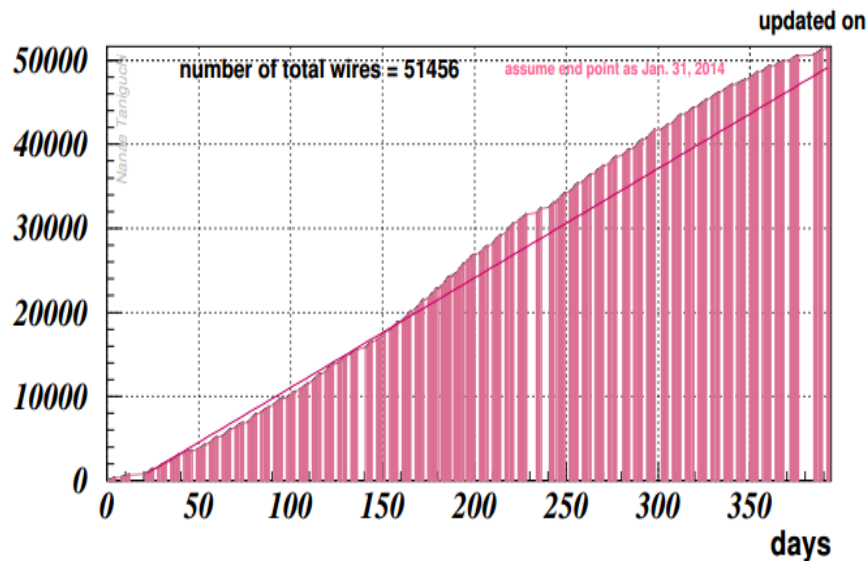


# Inner chamber

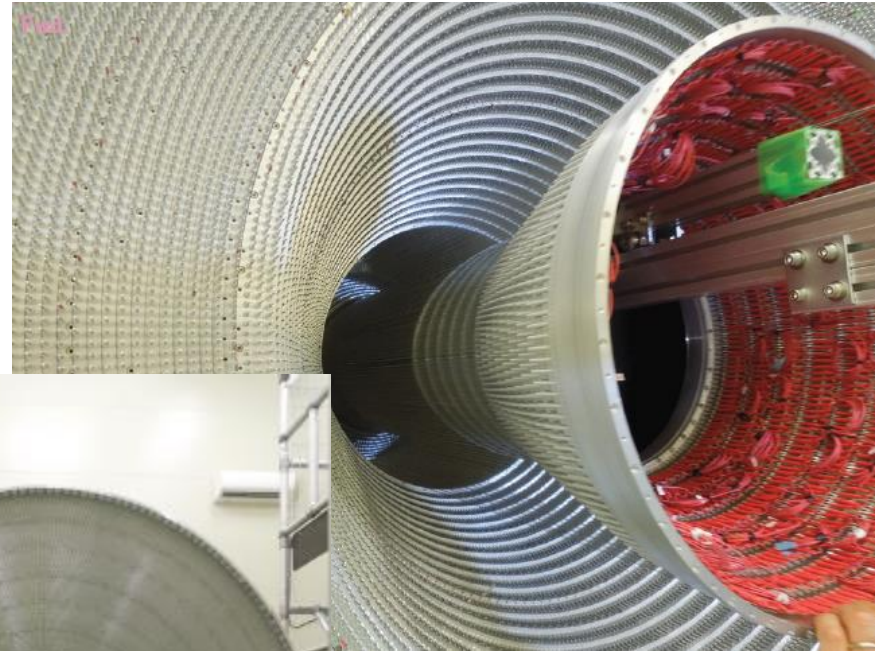


# Completed wire work

- All wire (sense + field 51456 wires) work is completed in Jan. 2014



# Installation of small-cell chamber



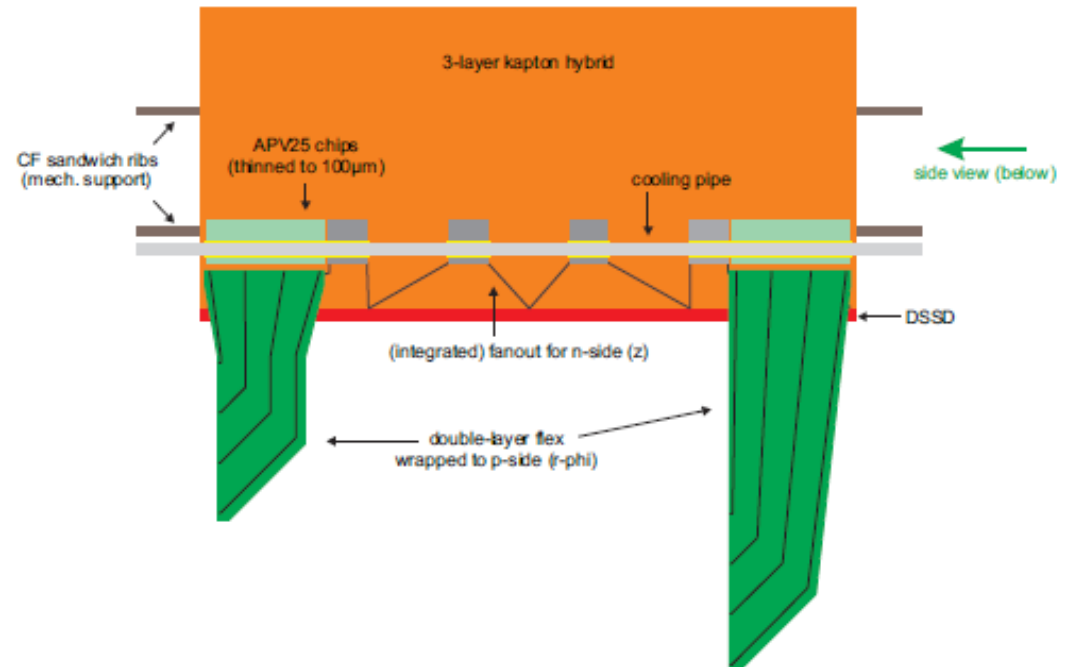
# Summary

- Belle II luminosity is 40 times higher than Belle
- To improve or keep adequate performance, high rate capability and high background immunity are to be implemented
- PXD and SVD
  - Design and operation verification are finished
  - We are preparing mass production
- CDC
  - Completed wire stringing
  - Integration with the readout electronics is ongoing

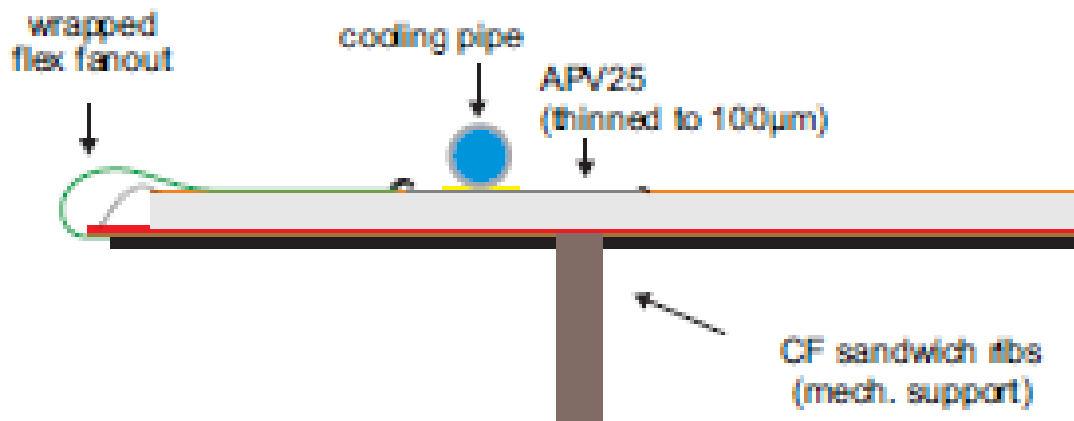
**BACKUP**

# The chip on sensor

a) Top view:



b) Side view (cross section):



# CDC performance from TDR

$$\sigma_{r\phi} = 100 \mu\text{m}, \sigma_z = 2 \text{ mm}$$

$$\sigma_{p_t}/p_t = \sqrt{(0.2\%p_t)^2 + (0.3\%/\beta)^2}$$

$$\sigma_{p_t}/p_t = \sqrt{(0.1\%p_t)^2 + (0.3\%/\beta)^2} \text{ (with SVD)}$$

$$\sigma_{dE/dx} = 5\%$$

---